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of

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Complete if Known

Application Number	Not Yet Assigned
Filing Date	June 23, 2003
First Named Inventor	Mitsuru SEKIGUCHI
Art Unit	2813
Examiner Name	Not Yet Assigned

Attorney Docket Number 740819-1014

U.S. PATENT DOCUMENTS

Examiner Initials ¹	Cite No. ¹	U.S. Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
		US-6,181,012 B1	01/30/2001	Edelstein et al	
		US-6,242,808 B1	06/05/2001	Shimizu et al	
		US-6,123,825	09/26/2000	Uzoh et al	
		US-6,130,156	10/10/2000	Havemann et al	
		US-			

FOREIGN PATENT DOCUMENTS

Examiner Initials ¹	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁴
		Country Code ³ Number ⁴ (if known)				
		JP 02-114639 A	04/26/1990	Seiichi		W/Abstract

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials ¹	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		P.J. Ding et al., "Oxidation resistant high conductivity copper films", Appl. Phys. Lett. 64, No. 21, pp. 2897-2899, May 23, 1994	
		C Ryu et al., "Effect of Texture on the Electromigration of CVD Copper", IEEE, pp. 201-205, 1997	
		M. Hasunuma et al., "Copper Reflow Process With Redox Cycle Reaction", The 42 nd Spring Meeting of the Japan Society of Applied Physics, No. 2, p. 810, 30a-K-6, March 1995, with English Translation	

Examiner Signature

Date Considered

3/17/04

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